

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Gormley et al.

GROUP: 2822

SERIAL NO: 10/617,427

EXAMINER: P.E. Perkins

FILED: July 11, 2003

FOR: A METHOD FOR FORMING A MICRO-MECHANICAL
COMPONENT IN A SEMICONDUCTOR WAFER, AND A
SEMICONDUCTOR WAFER COMPRISING A MICRO-
MECHANICAL COMPONENT FORMED THEREIN

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Sir:

AMENDMENT

In response to the Office Action mailed August 31, 2005, please amend the
above-identified application as follows